

WHAT IS CLAIMED IS:

Sub A17  
1. An epoxy resin composition that seals a semiconductor chip, wherein a color difference between a color of said epoxy resin and a color of a standard substance stored in a colorimeter shows a value of 30 or more.

2. An epoxy resin composition that seals a semiconductor chip, said epoxy resin composition including an epoxy resin and a filler that fills an inside of said epoxy resin, wherein said filler contains from 10 to 15 wt% of a filler component having an average particle size of 10  $\mu$ m or less with respect to total filler components.

3. A semiconductor device including:  
a semiconductor chip;  
a package formed of an epoxy resin that seals said semiconductor chip; and  
a laser mark printed on a surface of said package, wherein a color difference between a color of said laser mark and a color of the surface of said package where the laser mark is not formed, as measured by means of a colorimeter, shows a value of 10 or more.

Sub C17  
4. ~~The semiconductor device according to claim 3, wherein said package is colored with a dye.~~

Sub A17  
5. A semiconductor device including:  
a semiconductor chip;  
a package formed of an epoxy resin that seals said semiconductor chip; and  
a laser mark printed on a surface of said package, wherein a color difference between a color of said epoxy resin and a color of a standard substance stored in a colorimeter shows a value of 30 or more.

6. A semiconductor device including:

Sub  
A-5  
Conc. 14. >

a semiconductor chip;  
a package formed of an epoxy resin that seals said semiconductor chip; and

- 5 a filler that fills an inside of said epoxy resin, wherein said filler contains from 10 to 15 wt% of a filler component having an average particle size of 10  $\mu\text{m}$  or less with respect to total filler components.

7. A method of judging a visibility of a laser mark printed on a surface of a package in a semiconductor device sealed with the package formed of an epoxy resin, said method including the steps of:

- 5 measuring a color difference value between a color of said laser mark and a color of the surface of said package where the laser mark is not formed, by means of a colorimeter; and  
judging whether said color difference value shows a value of 10 or more.